

M74HC651 M74HC652

HC651 OCTAL BUS TRANSCEIVER/REGISTER (3-STATE, INV.) HC652 OCTAL BUS TRANSCEIVER/REGISTER (3-STATE)

- HIGH SPEED
- $f_{MAX} = 73 \text{ MHz (TYP.)} \text{ AT V}_{CC} = 5 \text{V}$
- LOW POWER DISSIPATION $I_{CC} = 4 \mu A \text{ (MAX.)} \text{ AT } I_{A} = 25 \text{ °C}$
- HIGH NOISE IMMUNITY

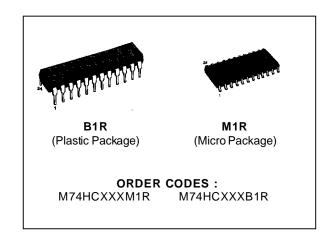
 V_{NIH} = V_{NIL} = 28 % V_{CC} (MIN.)
- OUTPUT DRIVE CAPABILITY
 15 LSTTL LOADS
- SYMMETRICAL OUTPUT IMPEDANCE | I_{OH} | = I_{OL} = 6 mA (mIN.)
- BALANCED PROPAGATION DELAYS tplh = tphl
- WIDE OPERATING VOLTAGE RANGE Vcc (OPR) = 2 V TO 6 V
- PIN AND FUNCTION COMPATIBLE WITH 54/74LS651/652

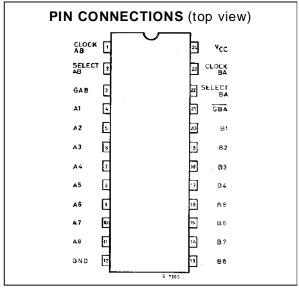
DESCRIPTION

M74HC651/652 are high speed CMOS OCTAL BUS TRANSCEIVERS AND REGISTERS (3-STATE), fabricated in silicon gate C²MOS technology. They have the same high speed performance of LSTTL combined with true CMOS low power consumption. These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal storage registers. Enable GAB and GBA are provided to control the transceiver functions.

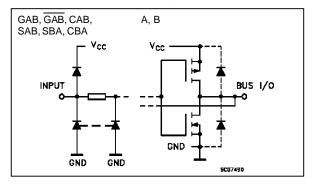
Select AB and Select BA control pins are provided to select whether real-time or stored data is transfered. A low input level selects real-time data, and a high selects stored data.

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock pins (CLOCK AB or CLOCK BA) regardless of the select or enable control pins. When select AB and select BA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling GAB and GBA. In this configuration each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state. All inputs are equipped with protection circuits against static discharge and transient excess voltage.



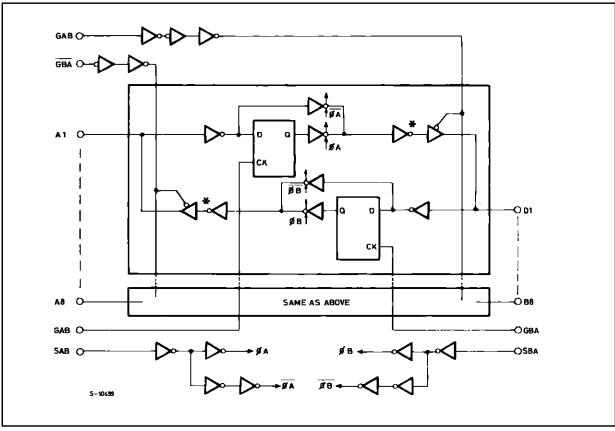


INPUT AND OUTPUT EQUIVALENT CIRCUIT



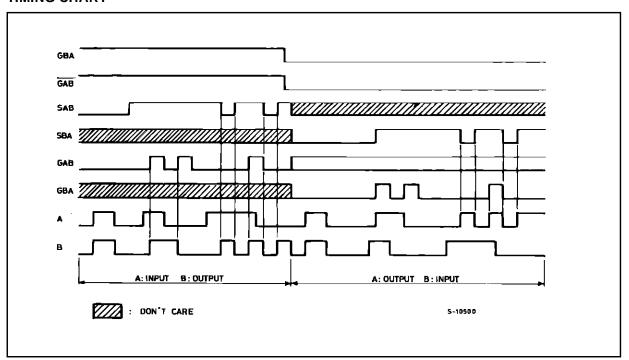
October 1993 1/12

LOGIC DIAGRAM (HC652)



Note: In case of M74HC652 output inverter marked * at A bus and B bus are eliminated.

TIMING CHART



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TRUTH TABLE HC652 (The truth table for HC651 is the same as this, but with the outputs inverted)

GAB	GBA	CAB	СВА	SAB	SBA	Α	В	FUNCTION
						INPUTS	INPUTS	Both the A bus and the B bus are inputs
١.		Х	Х	Х	Х	Z	Z	The output functions of the A and B bus are disabled
L	Н		占	Х	Х	INPUTS	INPUTS	Both the A and B buz are used for inputs to the internal flip-flops. Data at the bus will be stored on low to high transition of the clock inputs
						OUTPUTS	INPUTS	The A bus are outputs and the B bus are inputs
		X*	Х	Х	L	L	L	The data at the B bus are displayed at the A bus
						Н	Н	
		X*	\Box	Х	L	L	L	The data at the B bus ar displayed at the A bus.
L	L					Н	Н	The data of the B bus are stored to the internal flip-flop on low to high transition of th clock pulse
		X*	Х	Х	Н	Qn	X	The data stored to the internal flip-flop are dispayed at the A bus
		X*		Х	Н	L	L	The data at the B bus are stored to the internal flip-
						Н	Н	flop on low to high transition of the clock pulse. The states of the internal flip-flops output directly to the A bus
						INPUTS	OUTPUTS	The A bus are inputs and the B bus are outputs
		Х	X*	L	Х	L	L	The data at the A bus are displayed at the B bus
			^		^	Н	Н	
			Χ*	L	Х	L	L	The data at the A bus are displayed at the B bus.
н	н					Н	Н	The data of the A bus are stored to the internal flip- flop on low to high transition of the clock pulse
		Х	X*	Н	Х	X	Qn	The data stored to the internal flip-flops are displayed at the B bus
			X*	Н	Х	L	L	the data at the A bus are stored to the internal flip-
						Н	Н	flop on low to high transition of the clock pulse. The states of the internal flip-flops output directly to the B bus
						OUTPUTS	OUTPUTS	Both the A bus and the B bus are outputs
Н	L	Х	Х	Н	Н	Qn	Qn	The data stored to the internal flip-flops are displayed at the A and B bus respectively
	<u>-</u>	J	<u></u>	Н	Н	Qn	Qn	The output at the A bus are displayed at the B bus, the output at the B bus are displayed at the A bus respectively

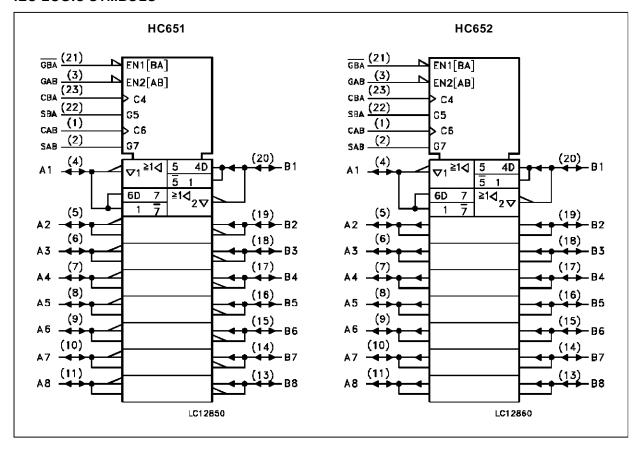
[:] DON'T CARE

Z: HIGH IMPEDANCE
Qn: THE DATA STORED TO THE INTERNAL FLIP-FLOPS BY MOST RECENT LOW TO HIGH TRANSITION OF THE CLOCK INPUTS
THE DATA AT THE A AND B BUS WILL BE STORED TO THE INTERNAL FLIP-FLOPS ON EVERY LOW TO HIGH TRANSITION OF THE CLOCK INPUTS

PIN DESCRIPTION

PIN No	SYMBOL	NAME AND FUNCTION
1	CLOCK AB	A to B Clock Input (LOW to HIGH, Edge-Trigged)
2	SELECT AB	Select A to B Source Input
3	GAB	Direction Control Input
4, 5, 6, 7, 8, 9, 10, 11	A1 to A8	A data Inputs/Outputs
20, 19, 18, 17, 16, 15, 14, 13	B1 to B8	B Data Inputs/Outputs
21	GBA	Output Enable Input (Active LOW)
22	SELECT BA	Select B to A Source Input
23	CLOCK BA	B to A Clock Input (LOW to HIGH, Edge-Triggered)
12	GND	Ground (0V)
24	Vcc	Positive Supply Voltage

IEC LOGIC SYMBOLS



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vcc	Supply Voltage	-0.5 to +7	V
VI	DC Input Voltage	-0.5 to V _{CC} + 0.5	V
Vo	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	± 20	mA
lok	DC Output Diode Current	± 20	mA
lo	DC Output Source Sink Current Per Output Pin	± 35	mA
Icc or I _{GND}	DC V _{CC} or Ground Current	± 70	mA
P _D	Power Dissipation	500 (*)	mW
T _{stg}	Storage Temperature	-65 to +150	°C
TL	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied. (*) 500 mW: \cong 65 °C derate to 300 mW by 10mW/°C: 65 °C to 85 °C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Value	Unit	
V_{CC}	Supply Voltage	2 to 6	V	
VI	Input Voltage	0 to V _{CC}	V	
Vo	Output Voltage		0 to V _{CC}	V
T _{op}	Operating Temperature:		-40 to +85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 2 V	0 to 1000	ns
		V _{CC} = 4.5 V	0 to 500	
		V _{CC} = 6 V	0 to 400	

DC SPECIFICATIONS

		T	est Co	nditions	Value					
Symbol	Parameter	Vcc			Т	Γ _A = 25 °C		-40 to 85 °C		Unit
		(V)			Min.	Тур.	Max.	Min.	Max.	
V _{IH}	High Level Input Voltage	2.0			1.5			1.5		
		4.5			3.15			3.15		V
		6.0			4.2			4.2		
VIL	Low Level Input	2.0					0.5		0.5	
	Voltage						1.35		1.35	V
		6.0					1.8		1.8	
V_{OH}	High Level Output Voltage	2.0	V _I =		1.9	2.0		1.9		
		4.5	VI – VIH	I ₀ =-20 μA	4.4	4.5		4.4] ,,
		6.0	or		5.9	6.0		5.9		V
			V _{IL}	I _O =-6.0 mA	4.18	4.31		4.13		
		6.0		I _O =-7.8 mA	5.68	5.8		5.63		
V_{OL}	Low Level Output Voltage	2.0	V _I =			0.0	0.1		0.1	
		4.5	VIH	I _O = 20 μA		0.0	0.1		0.1	.,
		6.0	or			0.0	0.1		0.1	V
		4.5	V _{IL}	$I_O=6.0 \text{ mA}$		0.17	0.26		0.37	
		6.0		I _O = 7.8 mA		0.18	0.26		0.37	
II	Input Leakage Current	6.0	V _I = '	V _{CC} or GND			±0.1		±1	μΑ
l _{OZ}	3 State Output Off State Current	6.0		V _{IH} or V _{IL} V _{CC} or GND			±0.5		±5.0	μΑ
Icc	Quiescent Supply Current	6.0	V _I = '	V _{CC} or GND			4		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 6 \text{ ns}$)

		To	Test Conditions			Value				
Symbol	Parameter	Vcc	CL		T _A = 25 °C			-40 to 85 °C		Unit
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	
t _{TLH}	Output Transition Time	2.0				25	60		75	
t _{THL}		4.5	50			7	12		15	ns
		6.0				6	10		13	
t _{PLH}	Propagation Delay Time	2.0				74	150		190	
t _{PHL}	(BUS - BUS)	4.5	50			21	30		38	ns
		6.0				18	26		32	
		2.0				91	190		240	
		4.5	150			26	38		48	ns
		6.0				22	32		41	
t _{PLH}	Propagation Delay Time	2.0				98	210		265	
t _{PHL}	(CLOCK - BUS)	4.5	50			28	42		53	ns
		6.0				24	36		45	
		2.0				116	250		315	
		4.5	150			33	50		63	ns
		6.0				28	43		54	

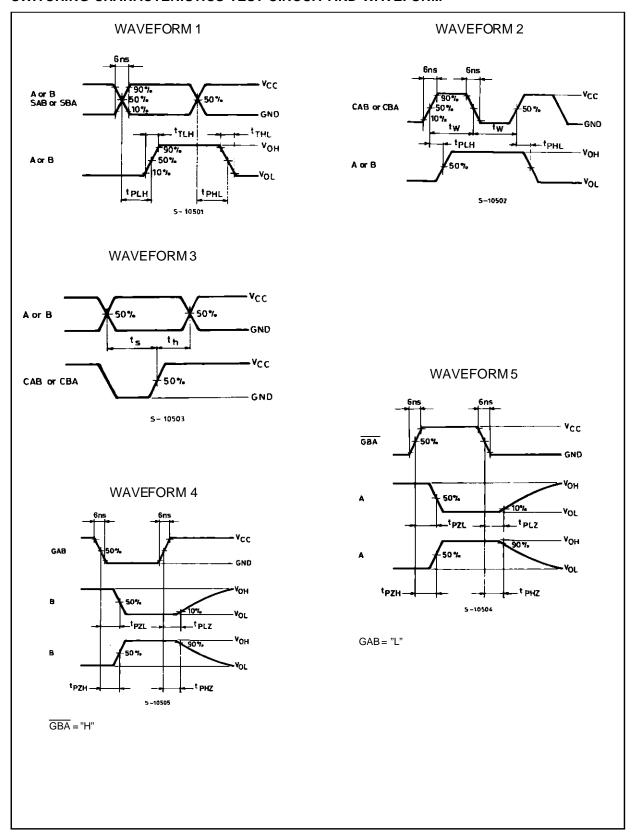


AC ELECTRICAL CHARACTERISTICS (Continued)

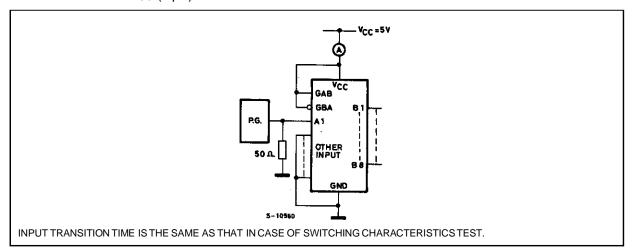
		To	est Co	nditions	Value					
Symbol	Parameter	Vcc			T	A = 25 °	,C	-40 to	85 °C	Unit
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	
t _{PLH}	Propagation Delay Time	2.0				81	170		215	
t_{PHL}	(SELECT - BUS)	4.5	50			23	34		43	ns
		6.0				20	29		37	
		2.0				98	210		265	
		4.5	150			28	42		53	ns
		6.0				24	36		45	
t _{PZL}	3-State Output Enable Time	2.0				74	175		220	
t _{PZH}	-	4.5	50	$R_L = 1 K\Omega$		21	35		44	ns
		6.0				18	30		37	
		2.0				91	215		270	
			150	$R_L = 1 K\Omega$		26	43		54	ns
		6.0				22	37		46	
t_{PLZ}	Output Disable Time	2.0				50	175		220	
t _{PHZ}		4.5	50	$R_L = 1 K\Omega$		21	35		44	ns
		6.0				18	30		37	
f_{MAX}	Maximum Clock Frequency	2.0			6	19		4.8		
		4.5	4.5 50		30	67		24		MHz
		6.0			35	79		28		
t _{W(H)}	Minimum Clock Pulse Width	2.0				30	75		95	
$t_{W(L)}$		4.5	50			7	15		19	ns
		6.0				6	13		16	
ts	Minimum Set-up Time	2.0				16	50		65	
		4.5	50			4	10		13	ns
		6.0				3	9		11	
t _h	Minimum Hold Time	2.0					5		5	
		4.5	50				5		5	ns
		6.0					5		5	
C _{IN}	Input Capacitance					5	10		10	pF
C _{I/O}	Bus Terminal Capacitance					10				pF
C _{PD} (*)	Power Dissipation Capacitance			r HC651 r HC652		39 38				pF

^(*) C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation. $I_{CC}(opr) = C_{PD} \bullet V_{CC} \bullet f_{IN} + I_{CC}/8$ (per Channel)

SWITCHING CHARACTERISTICS TEST CIRCUIT AND WAVEFORM

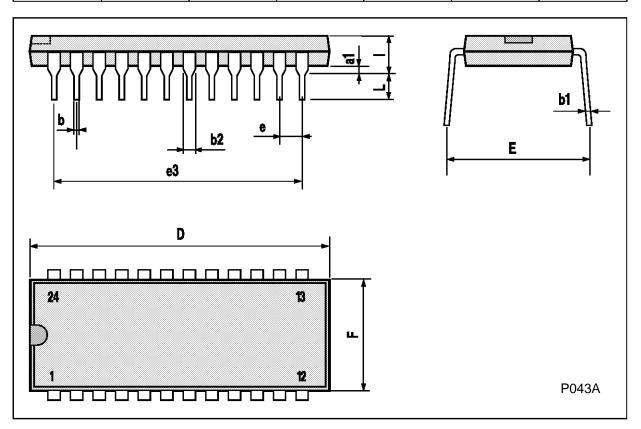


TEST WAVEFORM Icc (Opr.)



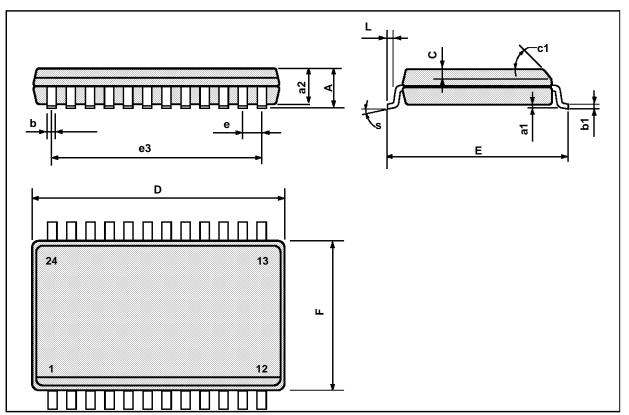
Plastic DIP24 (0.25) MECHANICAL DATA

DIM.		mm		inch				
2	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
a1		0.63			0.025			
b		0.45			0.018			
b1	0.23		0.31	0.009		0.012		
b2		1.27			0.050			
D			32.2			1.268		
E	15.2		16.68	0.598		0.657		
е		2.54			0.100			
e3		27.94			1.100			
F			14.1			0.555		
I		4.445			0.175			
L		3.3			0.130			



SO24 MECHANICAL DATA

DIM.		mm		inch							
Dilvi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.					
Α			2.65			0.104					
a1	0.10		0.20	0.004		0.007					
a2			2.45			0.096					
b	0.35		0.49	0.013		0.019					
b1	0.23		0.32	0.009		0.012					
С		0.50			0.020						
c1			45°	(typ.)							
D	15.20		15.60	0.598		0.614					
E	10.00		10.65	0.393		0.420					
е		1.27			0.05						
e3		13.97			0.55						
F	7.40		7.60	0.291		0.299					
L	0.50		1.27	0.19		0.050					
S		8° (max.)									



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